

A Ege Engin

List of Publications by Year in descending order

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33
papers

447
citations

1163117

8
h-index

1058476

14
g-index

33
all docs

33
docs citations

33
times ranked

249
citing authors

#	ARTICLE	IF	CITATIONS
1	Modeling of Crosstalk in Through Silicon Vias. IEEE Transactions on Electromagnetic Compatibility, 2013, 55, 149-158.	2.2	92
2	Multilayered Finite-Difference Method (MFDM) for Modeling of Package and Printed Circuit Board Planes. IEEE Transactions on Electromagnetic Compatibility, 2007, 49, 441-447.	2.2	77
3	Finite-Difference Modeling of Noise Coupling between Power/Ground Planes in Multilayered Packages and Boards. , 0, , .		38
4	Extraction of Dielectric Constant and Loss Tangent Using New Rapid Plane Solver and Analytical Debye Modeling for Printed Circuit Boards. IEEE Transactions on Microwave Theory and Techniques, 2010, 58, 211-219.	4.6	35
5	Power transmission lines: A new interconnect design to eliminate simultaneous switching noise. , 2008, , .		31
6	Closed-form network representations of frequency-dependent RLGC parameters. International Journal of Circuit Theory and Applications, 2005, 33, 463-485.	2.0	25
7	Efficient Sensitivity Calculations for Optimization of Power Delivery Network Impedance. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 332-339.	2.2	25
8	Virtual Ground Fence for GHz Power Filtering on Printed Circuit Boards. IEEE Transactions on Electromagnetic Compatibility, 2013, 55, 1277-1283.	2.2	15
9	Prediction and Comparison of High-Performance On-Chip Global Interconnection. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2011, 19, 1154-1166.	3.1	14
10	Analysis and Design of Electromagnetic Bandgap (EBG) Structures for Power Plane Isolation Using 2D Dispersion Diagrams and Scalability. , 2006, , .		13
11	Passive Multiport RC Model Extraction for Through Silicon Via Interconnects in 3-D ICs. IEEE Transactions on Electromagnetic Compatibility, 2014, 56, 646-652.	2.2	10
12	Analysis for Signal and Power Integrity Using the Multilayered Finite Difference Method. , 2007, , .		8
13	Virtual ground fence: A methodology for GHz power filtering on printed circuit boards. , 2012, , .		8
14	Fast EM/Circuit Transient Simulation Using Laguerre Equivalent Circuit (SLeEC). IEEE Transactions on Electromagnetic Compatibility, 2009, 51, 756-762.	2.2	7
15	Dielectric Constant and Loss Tangent Characterization of Thin High-K Dielectrics Using Corner-to-Corner Plane Probing. , 2006, , .		5
16	Metal semiconductor (MES) TSVs in 3D ICs: Electrical modeling and design. , 2012, , .		5
17	Virtual ground fence options for shielding power plane noise. , 2014, , .		5
18	Integration of Planar Antennas Considering Electromagnetic Interactions at Board Level. IEEE Transactions on Electromagnetic Compatibility, 2011, 53, 1005-1014.	2.2	4

#	ARTICLE	IF	CITATIONS
19	Power Plane Filter Using Higher Order Virtual Ground Fence. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2017, 7, 519-525.	2.5	4
20	Frequency-Dependent Dielectric Constant and Loss Tangent Characterization of Thin Dielectrics Using a Rapid Solver. , 2007, , .		3
21	An Arnoldi Algorithm for Power-Delivery Networks With Variable Dielectric Constant and Loss Tangent. IEEE Transactions on Electromagnetic Compatibility, 2010, 52, 859-865.	2.2	3
22	Modeling of coupled TSVs in 3D ICs. , 2012, , .		3
23	Debye Model Fitting for Time-Domain Modeling of Lossy Dielectrics. International Symposium on Microelectronics, 2010, 2010, 000422-000427.	0.0	3
24	Multi-layer fringe-field augmentations for the efficient modeling of package power planes. , 2008, , .		2
25	Automated dielectric constant and loss tangent characterization using cavity resonators. , 2011, , .		2
26	Power distribution network design and characterization using virtual ground fence. , 2012, , .		2
27	Higher-order virtual ground fence design for filtering power plane noise. , 2016, , .		2
28	Resonant-plane common-mode filter in differential lines. , 2017, , .		2
29	Equivalent circuit model extraction for interconnects in 3D ICs. , 2013, , .		1
30	Power archipelago for GHz power filtering on printed circuit boards. , 2015, , .		1
31	Determination of dielectric thickness, constant, and loss tangent from cavity resonators. , 2016, , .		1
32	Virtual Ground Fence: A Simple Method for Protection against High Frequency Simultaneous Switching Noise. International Symposium on Microelectronics, 2012, 2012, 001081-001084.	0.0	1
33	A Novel Approach to the Measurement and Characterization of Losses due to Surface Roughness in High Speed Transmission Lines. Additional Conferences (Device Packaging HiTEC HiTEN & CICMT), 2011, 2011, 000241-000245.	0.2	0